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POLISHING METHOD AND POLISHING APPARATUS

ABSTRACT OF THE DISCLOSURE

A method is provided for polishing a device wafer, which has projections and depressions formed on a surface thereof, with the use of an abrading plate. The method comprises polishing
5 the device wafer while supplying a surface active agent and/or while dressing a surface of the abrading plate. This method for polishing the device wafer can always exhibit a self-stop function, without being restricted by the composition of the abrading plate, and without being restricted by the type of the
10 substrate.

Figure 1



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